

CUSTOM MODULES (Commercial / Moisture Resistant / Hermetic)

Capabilities:

Customers looking for application specific custom power modules benefit from Powerex's years of experience in chip manufacturing and design / engineering. Powerex custom power modules employ performance proven features. Soldered-down and wire bonding fabrication and compression bonded encapsulation (CBE) of SCR / Diode elements offer increased switching speeds, lower losses, more efficient cooling and higher power handling capabilities.

Reliability / Qualification Testing:

Reliability and qualification testing can be performed in accordance to military specifications, including Group A, B and C and specific customer requirements.

Features:

- Different Circuit Configurations (i.e. Common Emitter, Chopper)
- Different Termination Styles (i.e. Thicker Bus Bars, D-sub Connectors, Press On Pins, etc.)
- Extended Temperature Range, -55°C to 200°C
- Hermetic Modules
- High Voltage Isolation
- Integrated Heatsinks – Both Air and Liquid Cooled by Eliminating the Baseplate
- Larger Free-wheel Diodes
- Low Module Weight
- Moisture Resistance
- Over-current Shutdown
- Package Height, Width and Length
- Temperature and Current Sense

Substrates:

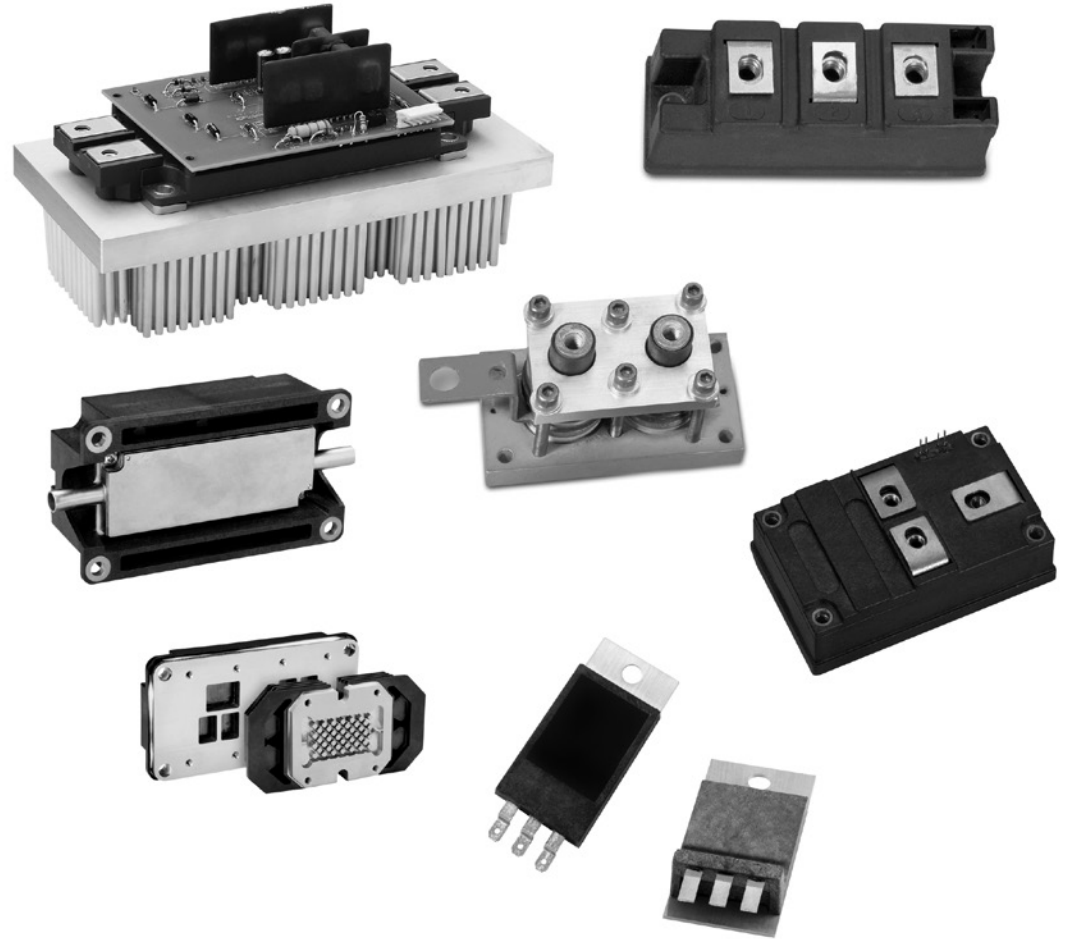
- Alumina
- Aluminum Nitride
- BeO
- IMS

Die Technology:

- Diode
- FR Diode
- GTO
- HVIGBT
- IGBT
- MOSFET
- SCR
- SiC Diode
- SiC MOSFET

Packages:

- Custom Development for Both Plastic and Hermetic Packages
- Picture Frame
- Standard IGBT Cases



VOLTAGE: 30V TO 15,000V
CURRENT: 50A TO 1600A

For more information:

visit: <http://www.pwr.com/summary/custom-power-modules.aspx>

email: globalsales@pwr.com

phone: 724-925-7272, Option 3 (Applications Engineering Assistance)

DC-DC
Converters

Gate Drivers
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Interface

Custom
Modules

IGBT
Assemblies

Assemblies

Fast Recovery
Diode Modules

Thyristor &
Diode
Modules

Discrete
Rectifiers

Discrete
Thyristors

DIPIPM

IPMs

MOSFET
Modules

Hybrid
& SiC
Modules

IGBTs